

5、Specification

TAI-TECH Part Number	Inductance L0 A(uH)	I rms (A)		I sat (A)		DCR (m Ω)	
		Typ	max	typ	max	typ	max
HPC252012BMV-R22Y	0.22	6.00	5.50	5.50	5.00	15	18
HPC252012BMV-R33M	0.33	5.20	4.80	4.80	4.40	20	24
HPC252012BMV-R47M	0.47	4.80	4.50	4.30	4.00	26	32
HPC252012BMV-R68M	0.68	4.40	4.00	3.70	3.50	37	45
HPC252012BMV-1R0M	1.0	3.60	3.30	3.00	2.80	50	60
HPC252012BMV-1R2M	1.2	3.40	3.10	2.90	2.70	61	74
HPC252012BMV-1R5M	1.5	3.10	2.80	2.70	2.50	70	84
HPC252012BMV-2R2M	2.2	2.70	2.30	2.10	1.90	94	113
HPC252012BMV-3R3M	3.3	2.20	1.90	1.70	1.50	126	152
HPC252012BMV-4R7M	4.7	1.80	1.60	1.50	1.30	225	270
HPC252012BMV-6R8M	6.8	1.50	1.30	1.20	1.10	310	372
HPC252012BMV-100M	10.0	1.30	1.10	1.00	0.90	495	594
HPC252012BMV-150M	15.0	1.00	0.90	0.80	0.70	650	780
HPC252012BMV-220M	22.0	0.80	0.60	0.63	0.58	908	1090

Note:

1. Test frequency : Ls : 100KHz /1.0V.
2. All test data referenced to 25°C ambient.
3. Testing Instrument(or equ) : Agilent 4284A,E4991A,4339B,KEYSIGHT E4980A/AL,chroma3302,3250,16502.
4. Heat Rated Current (I rms) will cause the coil temperature rise approximately ΔT of 40°C
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions. Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. I rms Testing : Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components. Therefore temperature rise should be verified in application conditions.
8. Rated DC current: The lower value of I rms and Isat.

11、Typical Performance Curves



